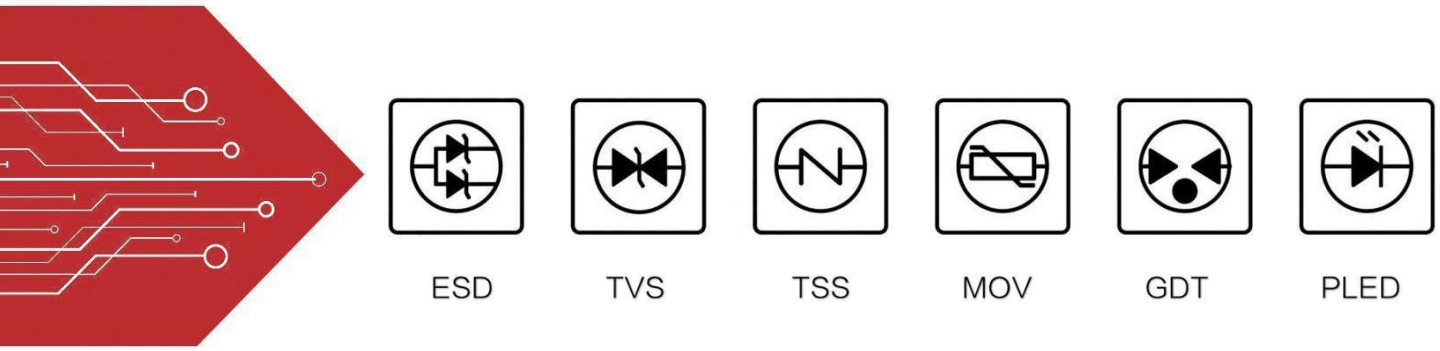
MSKSEMI
SEMICONDUCTOR



Product data sheet

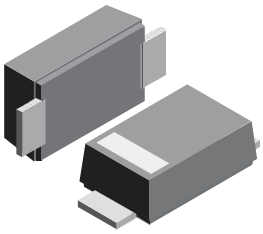
POWER: 200Wa t t s

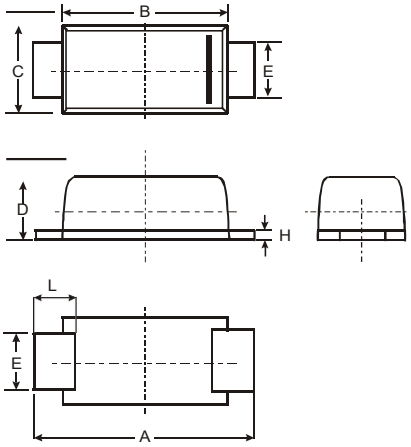
Features

- For surface mounted applications
- Low profile package
- Low incremental surge resistance, excellent clamping capability
- 200W peak pulse power capability with a10/1000 μs wave from,repetition rate (dutycycle):0.01%
- High temperature soldering guaranteed: 260 ℃/10 seconds, at terminals

Mechanical Data

- Case: JEDEC SOD-123FL, molded plastic over passivated chip
- Polarity: Color band denotes positiveend (cathode) except for bidirectional
- Mounting position: Any
- Weight: 0.006 ounces, 0.02 gram





SOD-123FL			
Dim	Min	Max	Typ
A	3.50	3.80	3.65
B	2.60	2.90	2.75
C	1.70	1.90	1.80
D	1.00	1.30	1.15
E	0.80	1.10	0.95
H	0.12	0.20	0.16
L	0.07	0.09	0.08
All Dimensions in mm			

Maximum Ratings T_A = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Maximum P_{PK} Dissipation (PW - 10/1000 μs)	P_{PK}	200	W
Maximum P_{PK} Dissipation @ Ta = 25 °C (PW - 8/10 μs) (Note 2)	P_{PK}	1000	W
DC Power Dissipation @ Ta = 25 °C (Note 3)	P_D	385	mW
Derate above 25 °C		4.0	mW/ °C
Thermal Resistance, Junction to Ambient (Note 3)	$R_{\Theta JA}$	325	°C/W
Thermal Resistance, Junction to Lead (Note 3)	$R_{\Theta JL}$	26	°C/W
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55 to +150	°C

Notes :

(1) Non−repetitive current pulse at Ta = 25°C, per waveform of Fig. 2.
(2) Non−repetitive current pulse at Ta = 25°C, per waveform of Fig. 5.
(3) Mounted with recommended minimum pad size, DC board FR4.

Electrical Characteristics

TYPE	Reverse Stand-Off Voltage	Breakdown Voltage Min. @I_T	Breakdown Voltage Max. @ I_T	Test Current	Reverse Leakage @V_{RWM}	Maximum Clamping Voltage @I_{PP}	Peak Pulse Current
	V_{RWM} (V)	$V_{BR\ MIN}$(V)	$V_{BR\ MAX}$(V)	I_T (mA)	I_R(uA)	V_C(V)	I_{PP} (A)
SSCT12V12D1	12	13.3	14.7	1.0	2.5	19.9	10.1

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